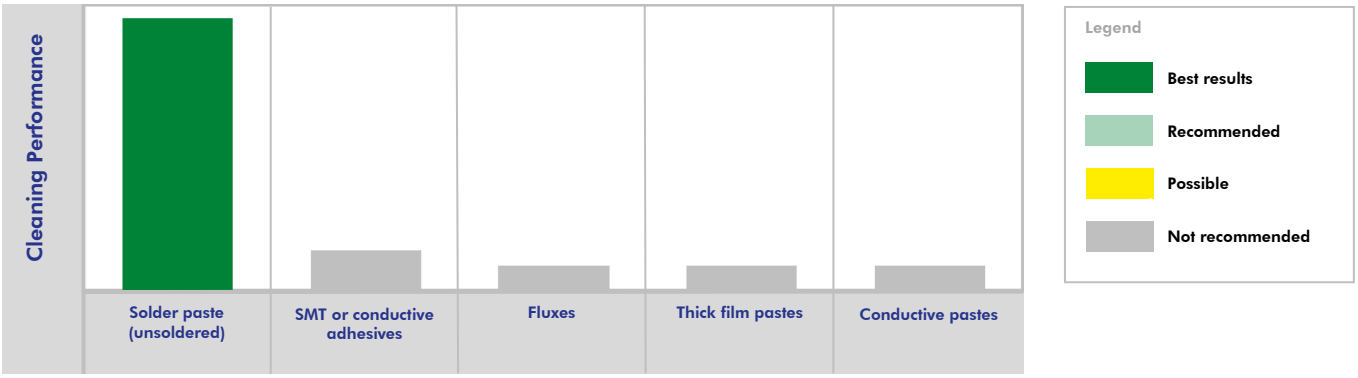
VIGON® UC 160

Water-based cleaning agent for stencil underside wiping in printers

VIGON® UC 160 is a water-based cleaning agent specifically designed to remove solder paste from stencils in SMT printers. It has an excellent wetting ability on the fabric, which leads to an improved cleaning performance and thereby reduces smearing on the stencil underside significantly. This in turn prevents solder paste bridging on boards and ensures good and reliable printing results. VIGON® UC 160 is also an ideal replacement for Isopropanol due to excellent health and safety characteristics.

Areas of application – Stencil underside wiping in SMT printers



Advantages compared to other cleaners

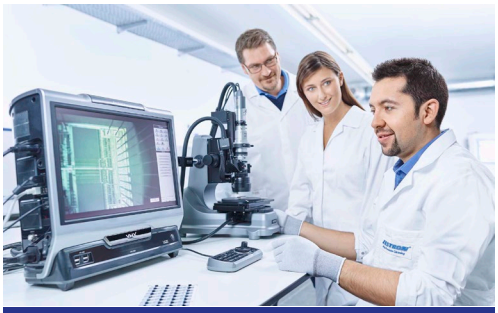
- VIGON® UC 160 effectively removes the latest lead-free & lead-based solder pastes from stencils in underside wiping, even out of fine pitch apertures.
- The cleaner is specifically suitable for print after wait.
- Provides excellent wetting ability on stencils and therefore increased cleaning performance, which significantly reduces smearing on the stencil underside. Thus, bridging of solder paste on the boards can be avoided.
- Good delineation stability further ensures reduced solder balling.
- High operational safety and ideal replacement for Isopropanol due to excellent health and safety characteristics, no flash point, low VOC level.
- VIGON® UC 160 has low odor.
- The product has been approved by leading international manufacturers for the use in their stencil printers. Written approvals can be obtained from ZESTRON.

Process Steps

Cleaning Process	1. Cleaning	2. Vacuum	3. Drying
SMT printer	VIGON® UC 160	Fabric	Fabric

Independent Test Center - Largest choice of leading machines, chemistry & analytics

Machine Test Center



Analytical Center

Visit our Machine Test Center and clean your stencils & screens under production conditions in cleaning machines of leading international equipment suppliers. Our process engineers will help you independently of any supplier to find the most suitable combination of equipment & cleaning agent for your requirements. Following the cleaning trials, all results will be reviewed immediately in our Analytical Center to verify the required cleanliness.

Contact ZESTRON's process engineers for cleaning trials:

Europe: +49 8453 41995 318; techsupport@zestron.com / South Asia: +604 (3996) 100; support@zestronasia.com

Technical Data

Density	(g/ccm) at 20°C/68°F	1.00
Surface tension	(mN/m) at 25°C/77°F	43.1
Boiling range	°C/°F	100 – 190 / 212 – 374
Flash point	°C/°F	None until boiling
pH value	10g/l H_2O	Neutral
Vapor pressure	(mbar) at 20°C/68°F	Approx. 21.0
Cleaning temperature	°C/°F	Room temperature
Application concentration	Ready-to-use	Pure
HMIS Rating	Health-Flammability-Reactivity	0 – 0 – 0

Product Features & Cleaning Standards

RoHS & WEEE Compliant	100% compliance with EU guidelines (RoHS 1, 2 & 3, WEEE)
Pb lead-free	Extensively tested and suitable for cleaning lead-free solder pastes
Reach Compliant	Product is free of any critical substances according to SIN & SVHC lists

After cleaning the underside of SMT stencils used for production with VIGON® UC 160, PCBs meet the requirements of the following standard:

- IPC-9202 Material and Process Characterization/Qualification

Environmental, health & safety regulations

- VIGON® UC 160 is water-based and biodegradable.
- The cleaning agent is formulated free of any halogenated compounds.
- The product is a non-hazardous material and according to EU standards does not require specific labeling.
- Refer to the SDS for specific handling precautions and instructions.

Availability & Storage

1 Liter	✓
5 Liter	✓
25 Liter	✓
200 Liter	✓

- Available as ready-to-use solution
- Store VIGON® UC 160 in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Further product information

- **Material Compatibility**
  Please review the Material Compatibility overview before using the cleaning agent.
- **Evaluation guideline**
  Guideline for stencil underside wiping in SMT printers.
- **Process reliability**
  Additional information about underside wiping in printers.
- **Safety data sheet**